



Material Content Data Sheet



Sales Product Name		BTS7010-1EPA		Issued		14. September 2018		
MA#		MA003401974						
Package		PG-TSDSO-14-22		Weight*		65.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.795	1.22	1.22	12230	12230
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		580	
	non noble metal	iron	7439-89-6	0.754	1.16		11597	
wire	non noble metal	copper	7440-50-8	30.617	47.09	48.32	470884	483206
	non noble metal	copper	7440-50-8	0.642	0.99	0.99	9872	9872
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.14		1357
encapsulation	plastics	epoxy resin	-	3.441	5.29		52915	
	inorganic material	silicondioxide	60676-86-0	25.878	39.80	45.23	397991	452263
leadfinish	non noble metal	tin	7440-31-5	1.642	2.52	2.52	25248	25248
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12551	12551
glue	plastics	epoxy resin	-	0.053	0.08		810	
	noble metal	silver	7440-22-4	0.248	0.38	0.46	3820	4630
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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